09/825,648

23 April 2003

L Number	Hits	Search Text	DB	Time stamp
1	6	(("6017437") or ("6183611") or ("6241825")).PN.	USPAT;	2003/04/23
			US-PGPUB;	12:26
			EPO; JPO;	
			DERWENT	
2	17	("3826558" "4086870" "5000827" "5024746"	USPAT	2003/04/23
		"5095848" "5256274" "5368711" "5429733"		11:56
		"5437777" "5441629" "5447615" "5516414"		
		"5830805" "5853559" "5885353" "5891251"		
		"6019164").PN		
3	2473	205/118,122,123,125,295,640.ccls. or	USPAT;	2003/04/23
		204/297.01,297.06,297.07,297.1.ccls.	US-PGPUB;	12:27
			EPO; JPO;	
		,	DERWENT	
4	2	(205/118,122,123,125,295,640.ccls. or	USPAT;	2003/04/23
		204/297.01,297.06,297.07,297.1.ccls.	US-PGPUB;	12:31
) and ((chuck or (wafer adj support) or platen or	EPO; JPO;	
		platform) near (adjustable or compliant or resilient or	DERWENT	
		deformable or tiltable))		
5	7	(205/118,122,123,125,295,640.ccls. or	USPAT;	2003/04/23
		204/297.01,297.06,297.07,297.1.ccls.	US-PGPUB;	12:36
) and ((chuck or (wafer adj support) or platen or	EPO; JPO;	
		platform or support) near (adjustable or compliant or	DERWENT	
		resilient or deformable or tiltable))		
6	686	(205/118,122,123,125,295,640.ccls. or	USPAT;	2003/04/23
		204/297.01,297.06,297.07,297.1.ccls.	US-PGPUB;	12:40
) and (wafer or microelectronic or semiconductor)	EPO; JPO;	
			DERWENT	
7	11	((205/118,122,123,125,295,640.ccls. or	USPAT;	2003/04/23
		204/297.01,297.06,297.07,297.1.ccls.	US-PGPUB;	12:33
) and (wafer or microelectronic or semiconductor))	EPO; JPO;	12.00
		and ((chuck or (wafer adj support) or platen or	DERWENT	
		platform or support) with (adjustable or compliant or	Jenne	
		resilient or deformable or tiltable))		
8	8	(205/118,122,123,125,295,640.ccls. or	USPAT;	2003/04/23
		204/297.01,297.06,297.07,297.1.ccls.	US-PGPUB;	12:39
) and ((chuck or (wafer adj support) or platen or	EPO; JPO;	12.09
		platform or support) near (adjustable or compliant or	DERWENT	
		resilient or deformable or tiltable or conformable or	Jenner	
		conforming))		
9	58692	204/\$.ccls.	USPAT;	2003/04/23
		4	US-PGPUB;	12:39
			EPO; JPO;	12.00
			DERWENT	
10	70	204/\$.ccls. and ((chuck or (wafer adj support) or	USPAT;	2003/04/23
	, 5	platen or platform or support) near (adjustable or	US-PGPUB;	12:40
	į	compliant or resilient or deformable or tiltable or	EPO; JPO;	
		conformable or conforming))	DERWENT	
11	10	(204/\$.ccls. and ((chuck or (wafer adj support) or	USPAT;	2003/04/23
		platen or platform or support) near (adjustable or	US-PGPUB;	12:40
		compliant or resilient or deformable or tiltable or	EPO; JPO;	
		conformable or conforming))) and (wafer or	DERWENT	
		microelectronic or semiconductor)	50	

18	7	6019164.URPN.	USPAT	2003/04/23
				12:45